

PCN Number:	20181102000.0	PCN Date:	November 05, 2018
Title:	Datasheet for TMS320f280040-TMS320f280041, TMS320f280045, TMS320f280048-TMS320f280049		
Customer Contact:	PCN Manager	Dept:	Quality Services
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Material
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Bump Process
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Site
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Materials
<input type="checkbox"/>		<input type="checkbox"/>	Wafer Fab Process

Notification Details

Description of Change:

Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.



TMS320F280049, TMS320F280049C
TMS320F280048, TMS320F280048C, TMS320F280045
TMS320F280041, TMS320F280041C, TMS320F280040, TMS320F280040C

SPRS945D – JANUARY 2017 – REVISED OCTOBER 2018

Changes from December 15, 2017 to October 23, 2018 (from C Revision (December 2017) to D Revision)	Page
• Global: Replaced references to <i>TMS320C28x Floating Point Unit and Instruction Set Reference Guide</i> with references to <i>TMS320C28x Extended Instruction Sets Technical Reference Manual</i>	1
• Section 1.3 (Description): Added "C2000™ 32-bit microcontrollers are optimized for processing, sensing, and actuation ..." paragraph and "To learn more about the C2000 MCUs ..." paragraph.	3
• Section 3.1 (Related Products): Updated section.	10
• Table 4-1 (Pin Attributes): Updated DESCRIPTION of GPIO22_VFBSW, GPIO23_VSW, X1, XRSn, and VDDIO_SW.	15
• Table 4-3 (Digital Signals): Updated DESCRIPTION of GPIO22_VFBSW and GPIO23_VSW.	28
• Table 4-4 (Power and Ground): Updated DESCRIPTION of VDDIO_SW.	28
• Table 4-5 (Test, JTAG, Voltage Regulator, and Reset): Updated DESCRIPTION of XRSn.	28
• Table 4-10 (Connections for Unused Pins): Updated ACCEPTABLE PRACTICE for VREFHix.	51
• Section 5.8 (Thermal Design Considerations): Added section.	63
• Section 5.9.1.3 (Power Sequencing): Updated section.	66
• Section 5.9.5 (Emulation/JTAG): Added description of cJTAG.	80
• Figure 5-54 (eCAP Block Diagram): Updated footnote.	127
• Figure 5-55 (HRCAP Block Diagram): Updated footnote.	130
• Figure 5-58 (ePWM Submodules and Critical Internal Signal Interconnects): Updated figure.	134
• Section 5.11.6 (Sigma-Delta Filter Module (SDFM)): Added NOTE about avoiding noise on the SDx_Cy input. ...	142
• Section 5.11.6.1 (SDFM Electrical Data and Timing): Changed table title of Table 5-65 from "SDFM Timing Requirements" to "SDFM Timing Requirements When Using Asynchronous GPIO (ASYNC) Option".	144
• Section 5.11.6.1: Added WARNING about SDFM clock inputs.	144
• Section 5.11.6.2 (SDFM Electrical Data and Timing (Synchronized GPIO)): Added section.	146
• Section 6.3.2 (Control Law Accelerator (CLA) ROM Memory Map): Added section.	182
• Table 6-9 (Bus Master Peripheral Access): Added FSI to COMMUNICATIONS PERIPHERALS group.	190
• Section 6.9.1 (Configuring Alternate Boot Mode Select Pins): Changed section title from "Configuring Alternate Boot Mode Pins" to "Configuring Alternate Boot Mode Select Pins".	198
• Table 6-15 (BOOTPIN_CONFIG Bit Fields): Updated DESCRIPTION of BMSP2 and BMSP1.	198
• Table 6-17 (BOOTDEF Bit Fields): Updated table.	199
• Section 6.9.3 (GPIO Assignments): Updated section.	199
• Table 6-18 (SCI Boot Options): Updated OPTION column.	199
• Table 6-19 (CAN Boot Options): Updated OPTION column.	200
• Table 6-20 (Flash Boot Options): Updated OPTION column.	200
• Table 6-21 (Wait Boot Options): Updated OPTION column.	200
• Table 6-23 (I2C Boot Options): Updated OPTION and BOOTDEFx VALUE columns.	201
• Table 6-24 (Parallel Boot Options): Updated OPTION column.	201
• Table 6-25 (RAM Boot Options): Added table.	201
• Section 6.10 (Dual Code Security Module): Added section.	202
• Figure 6-4 (Windowed Watchdog): Updated figure.	203
• Section 8.2 (Tools and Software): Added F280049C controlCARD Evaluation Module and UniFlash Standalone Flash Tool.	206

The datasheet number will be changing.			
Device Family		Change From:	Change To:
TMS320f280040-TMS320f280041,TMS320f280045, TMS320f280048-TMS320f280049		SPRS945C	SPRS945D
These changes may be reviewed at the datasheet links provided. http://www.ti.com/product/tms320f280040			
Reason for Change:			
To accurately reflect device characteristics.			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):			
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.			
Changes to product identification resulting from this PCN:			
None.			
Product Affected:			
F280040CPMQR	F280041PMSR	F280045PZS	F280049CPZS
F280040PMQR	F280041PZQR	F280045PZSR	F280049PMS
F280041CPMS	F280041PZS	F280048CPMQR	F280049PMSR
F280041CPZQR	F280041PZSR	F280048PMQR	F280049PZQR
F280041CPZS	F280045PMS	F280049CPMS	F280049PZS
F280041PMS	F280045PMSR	F280049CPZQR	F280049PZSR

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